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**IN THE CLAIMS:**

**Please amend claims 1, 5, and 7-11, as follows:**

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1. (Amended) A surface acoustic wave (SAW) filter device with a chip substrate of a piezoelectric material, comprising:

$\beta^9$  a plurality of interdigital transducers accommodated in a plastic package;

a terminal member connected to said plastic package, wherein said terminal member comprises a lateral extending portion recessed into said package which contacts the back surface of the chip substrate,

wherein common potential means for providing a common potential in the interdigital transducers, charge neutralizing means for neutralizing charge generated on the chip substrate due to polarization, or charge escape means for causing escape of charge generated on the chip substrate due to polarization, is provided as electric discharge preventing means for preventing electric discharge among the plurality of interdigital transducers on the chip substrate.

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$\beta^{10}$  5. (Amended) The SAW filter device according to claim 1, wherein the electric discharge preventing means is realized by opposed portions of the interdigital transducers having non-sharp shapes.

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$\beta^{11}$  7. (Amended) The SAW filter device according to claim 1, wherein the electric discharge prevention means is realized by a high resistivity pattern provided so as to surround the front surface center portion of the chip substrate.

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8. (Amended) A surface acoustic wave (SAW) filter device with a chip substrate of a piezoelectric material, comprising:

a plurality of interdigital transducers and accommodated in a plastic package,

B" wherein said plastic package comprises a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion,

wherein a first pattern as an extension of part of the interdigital transducers, a second pattern spaced apart from the first pattern and a dummy electrode pattern connected to the second pattern are formed on the front surface of the chip substrate as an electric discharge preventing means for preventing electric discharge among the plurality of interdigital electric patterns.

9. (Amended) An SAW filter device with a chip substrate of a piezoelectric material having a plurality of interdigital transducers and accommodated in a plastic package,

wherein an electric discharge preventing means for preventing electric discharge among the plurality of interdigital electric patterns is realized by opposed portions of the interdigital transducers having non-sharp shapes.

10. (Amended) A package for accommodating a surface acoustic wave (SAW) filter formed on the front surface of a chip substrate, comprising:

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a plurality of terminals extending out of the package and extending into the package, wherein one of said terminals comprises an L-shaped portion, and wherein the back surface of said chip substrate contacts said L-shaped portion.

11. (Twice Amended) A surface acoustic wave (SAW) filter device with a chip substrate of a piezoelectric material, comprising:

a plurality of interdigital transducers and accommodated in a plastic package, said plastic package comprising a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic such that the back surface of the chip substrate is in contact with the L-shaped portion,

wherein common potential means for providing a common potential in the interdigital transducers, charge neutralizing means for neutralizing charge generated on the chip substrate due to polarization, or charge escape means for causing escape of charge generated on the chip substrate due to polarization, is provided as electric discharge preventing means for preventing electric discharge among the plurality of interdigital transducers on the chip substrate.

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**Please add the following new claims:**

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✓ 21. (New) A surface acoustic wave (SAW) device, comprising:

a chip substrate having a front surface and a back surface and formed from a piezoelectric material;

B12 a plurality of interdigital transducers formed on the front surface of said chip substrate;

a high resistivity thin film provided between the chip substrate and the interdigital transducers, wherein said high resistivity film prevents electric discharge among the plurality of interdigital transducers on the chip substrate;

a plastic package receiving said SAW filter; and

a plurality of terminal members connected to said plastic package, wherein one of said terminal members comprises a lateral extending portion recessed into said package which contacts the back surface of said chip substrate.

22. (New) The SAW device according to claim 21, wherein said high resistivity thin film substantially covers the entire interdigital transducer.

23. (New) The SAW device according to claim 21, further comprising:

a conductive material film covering the front surface of the chip substrate and the interdigital transducers.

24. (New) The SAW device according to claim 21, wherein said high resistivity film

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substantially covers the front surface of said chip substrate.

25. (New) The SAW device according to claim 21, wherein said high resistivity film surrounds the front surface center portion of the chip substrate.

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26. (New) The SAW device according to claim 21, further comprising:  
a conductive material film covering the front surface of the chip substrate and the interdigital transducers.

27. (New) The SAW device according to claim 21, wherein said one of said terminal members comprises a plate extending out of the package and into the package to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

28. (New) The SAW device according to claim 22, further comprising:  
a terminal member extending out of the package and extending into the package, thereby forming an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

29. (New) The package for accommodating an SAW filter of claim 10, wherein said terminal comprising said L-shaped portion comprises a ground terminal.

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30. (New) The package for accommodating an SAW filter of claim 10, wherein said terminal comprising said L-shaped portion comprises a longitudinal portion extending out of said package and a lateral portion extending into said central rectangular recess, wherein said lateral portion extends into said recess to create a contact with said chip substrate.

31. (New) The SAW filter device of claim 1, wherein said terminal member comprises an L-shaped portion.

32. (New) The SAW filter device of claim 31, wherein the back surface of the chip substrate contacts the L-shaped portion.

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Concluded  
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